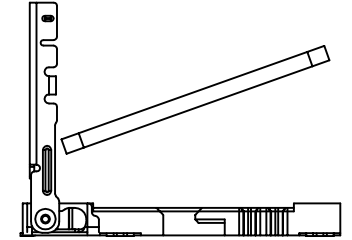
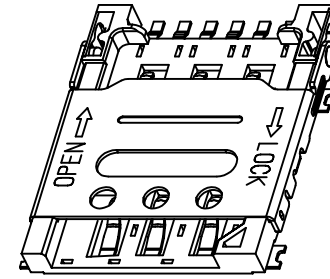
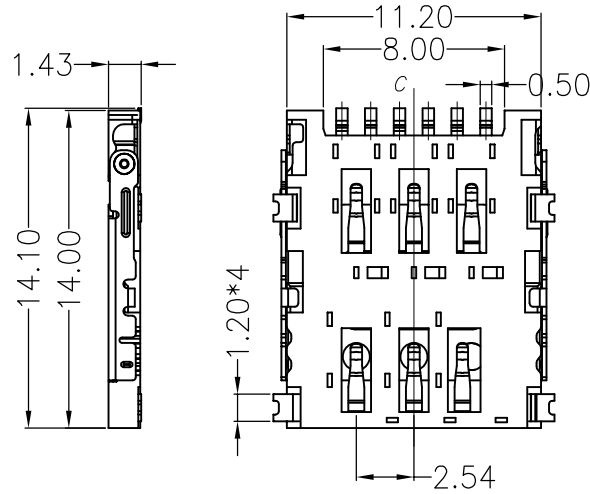
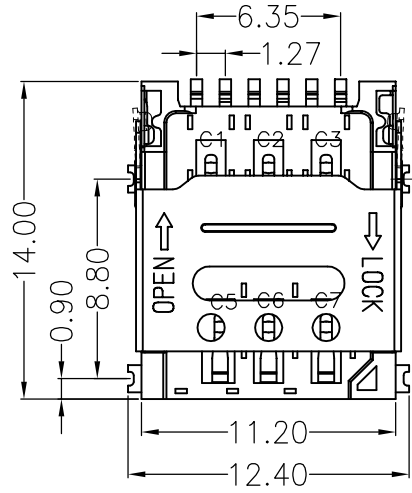
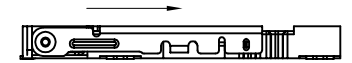


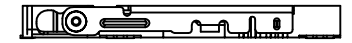
* All Raw Material, Manufacturing, Plating process comply with ROHS



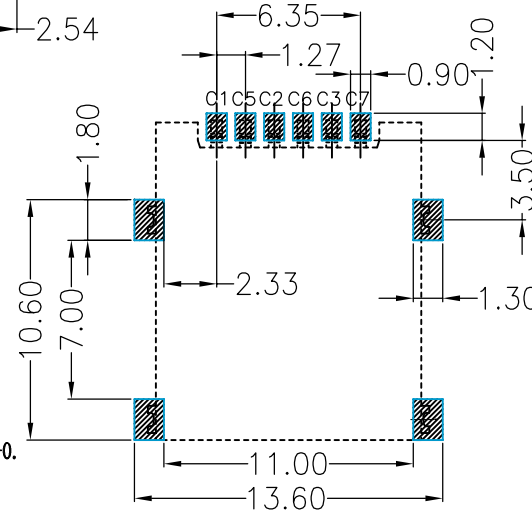
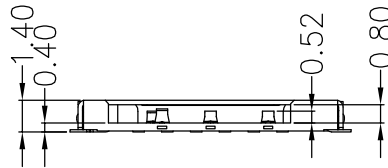
STEP 1 INSERT NANO SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH



PCB 焊盘区

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
SHELL: SUS

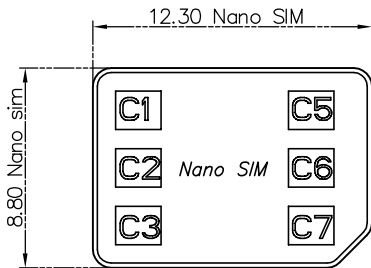
PLATING:

Contact: Plated 50u' Ni Overall Contact ALL Au 1U,
Shell: ALL NI 30U/MIN

Electrical:

Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:80m Ωmax.
Insulation Resistance:100M Ωmin./100V DC
Mating Cycles:5,000 Insertions
Reflow peak temp.: 260° C ±5° C, 3~5 S

PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				

东莞市汉博电子科技有限公司 Dongguan Hanbo Electronic Technology Co., Ltd			
DIMENSIONS UNIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.15 X.XX: ± 0.10 X.XXX: ± 0.05 ANGULAR: ± 1°	PRODUCT NAME : NANO-SIM 数量式1.40H 6P	DRAWING: COCO	DATE: 2017/11/20
	PRODUCT NO. : SNO-1330	CHECK: JANY	DATE: 2017/11/20
	DRAWING NO. :	APPROVED: 王岩	DATE: 2017/11/20
		SCALE: 1:1	DWG ID: C_D
		REV. : A	PAGE: 1 of 1